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## BIB DATA SHEET

CONFIRMATION NO. 1239

<b>SERIAL NUMBER</b> 10/577,173	<b>FILING or 371(c) DATE</b> 10/27/2009 <b>RULE</b>	<b>CLASS</b> 257	<b>GROUP ART UNIT</b> 2813	<b>ATTORNEY DOCKET NO.</b> 1441.141.101	
<b>APPLICANTS</b> Wolfgang Hetzel, Nattheim, GERMANY; Jochen Thomas, Munchen, GERMANY; <b>** CONTINUING DATA *****</b> This application is a 371 of PCT/DE2004/002374 10/25/2004 <b>** FOREIGN APPLICATIONS *****</b> GERMANY 103 50 239.4 10/27/2003 <b>** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **</b> 10/28/2009					
Foreign Priority claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No 35 USC 119(a-d) conditions met <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Verified and /JAMES M MITCHELL/ Acknowledged Examiner's Signature	<input type="checkbox"/> Met after Allowance Initials	<b>STATE OR COUNTRY</b> GERMANY	<b>SHEETS DRAWINGS</b> 2	<b>TOTAL CLAIMS</b> 20	<b>INDEPENDENT CLAIMS</b> 4
<b>ADDRESS</b> Dicke, Billig, & Czaja, PLLC 100 South 5th Street, Suite 2250 Minneapolis, MN 55402 UNITED STATES					
<b>TITLE</b> SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME					
<b>FILING FEE RECEIVED</b> 1230	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit		